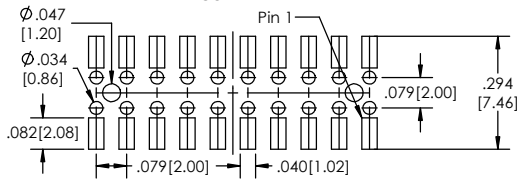
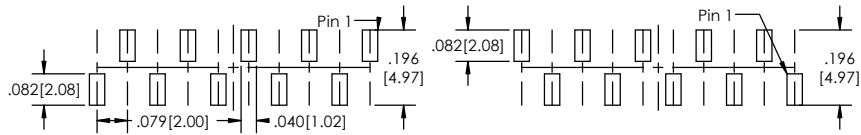


**Recommended P.C. Board Layout**  
SCALE 4:1

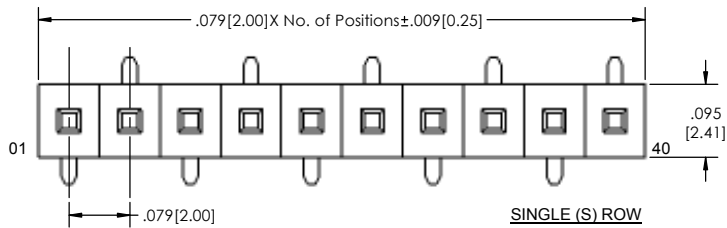
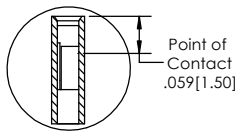


**DOUBLE ROW**

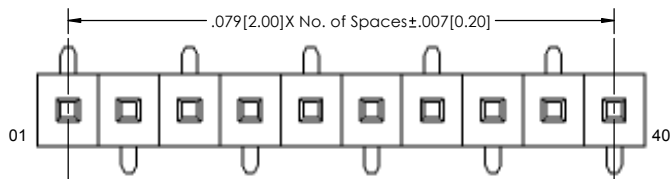


**SINGLE (S) ROW**

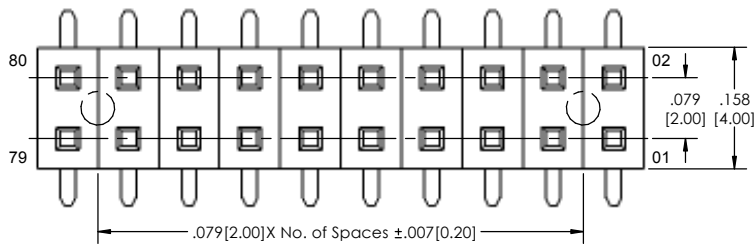
**SINGLE (M) ROW**



**SINGLE (S) ROW**

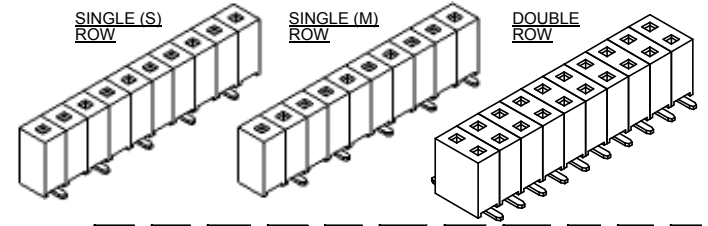
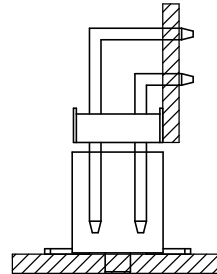


**SINGLE (M) ROW**



**DOUBLE ROW**

**APPLICATION**



SMBC-2 [XX] - [X] - [02] - [XX] - [V] - [XXX] - [X] - [XXX] - [X] - [XX] - [LF]  
(A) (B) (C) (D) (E) (F) (G) (H) (I) (J) (K)

- A. Pins Per Row
  - 1 through 40
- B. Row Specification
  - S= Single Row
  - D= Double Row
- C. Mounting Style
  - 02= Surface Mount
  - See Plating Options below
- D. Plating Options
- E. V= Vertical
- F. Polarized Position
  - Leave blank if not needed
  - If required, specify empty pin position
  - e.g. 012 for Pin 12
- G. Footprint (Option only for Single Row)
  - S= pin 1 right
  - M= pin 1 left
- H. Packing Information
  - TR= Tape and Reel
  - TB= Tube
  - If left blank, packaging at MLE's discretion
  - Pad may be metal, mylar or plastic
- I. Pad
  - P= Plastic
  - M= Metal
  - K= Kapton
  - O= No Pad
- J. Alignment Pin (Option only available for Double Row)
  - Leave blank if not needed
  - AP= With
- K. Lead Free

Mates with:  
 B5TC  
 B5TCM  
 B5TCR  
 B5TCRSM  
 B5TS  
 TB5TC  
 TB5TCM  
 TB5TS  
 TB5TCM  
 T5HC  
 T5HCR  
 T5HCRCR  
 T5HCRSM  
 T5HR  
 T5HRE  
 T5HS  
 T5HSCM  
 T5HC  
 T5HCR  
 T5HCRCR  
 T5HRE  
 T5HS  
 T5HSM

Plating options	
G	-10µ Gold on Contact Area/ Flash on Tail
T	-Matte Tin all Over
GT	-10µ Gold on Contact Area/ Matte Tin on Tail
H	-30µ Gold on Contact Area/ Matte Tin on Tail
F	-Gold Flash over Entire Pin
FT	- Gold Flash on Contact Area/ Matte Tin on Tail

**Specifications:**  
 Insertion Force- Single Contact only- H Plating:  
 3.7oz. [1.03N] avg with .0197 [0.50mm] sq. pin  
 Withdrawal Force- Single Contact only- H Plating:  
 2.2oz. [0.61N] avg with .0197 [0.50mm] sq. pin  
 Current Rating: 2.0 Ampere  
 Insulation Resistance: 1000M Ohms Min.  
 Dielectric Withstanding: 500V AC  
 Contact Resistance: 20M Ohms Max.  
 Operation Temperature: -40°C to +105°C  
 Max. Process Temperature  
 Peak: 260°C up to 10 secs.  
 Process: 230°C up to 60 secs.  
 Wave: 260°C up to 6 secs.  
 Reflow: 260°C up to 10 secs.  
 Manual Solder: 350°C up to 5 secs.

**Materials:**  
 Contact Material: Phosphor Bronze  
 Insulator Material: Nylon 6T  
 Plating: Au or Sn over 50µ" (1.27) Ni

Tails may be clipped to achieve specific dimensions.  
 Products cut to specific sizes are uncancellable/ nonreturnable.  
 Parts are subject to change without notice.

**ROHS COMPLIANT**  
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UNLESS OTHERWISE SPECIFIED:		NAME		DATE	
DIMENSIONS ARE IN INCHES		DRAWN	EOW	10/19/15	
TOLERANCES:		CHECKED	GW	10/19/15	
ONE DECIMALS ±.100		ENG APPR.			
THREE DECIMAL ±.005		MFG APPR.			ADDRESS: 2533 Centennial Blvd. Jeffersonville, IN 47130 Phone: 812-670-4174 Fax: 812-670-4175 E-Mail: mle@mlelectronics.com
FOUR DECIMAL ±.002		INTERPRET GEOMETRIC TOLERANCING PER:	MATERIAL		
NEXT ASSY	USED ON	FINISH	APPLICATION		REV <b>G</b> SHEET 1 OF 1